

Title (en)  
Method for temporary assembling a first substrate with a second substrate

Title (de)  
Verfahren zum zeitweiligen Verbinden eines ersten Substrats mit einem zweiten Substrat

Title (fr)  
Procédé d'assemblage temporaire d'un premier substrat avec un second substrat

Publication  
**EP 0970806 A1 20000112 (FR)**

Application  
**EP 99401726 A 19990709**

Priority  
LU 90262 A 19980710

Abstract (en)  
A polymer film (12) and/or second substrate is/are charged electrostatically with opposite polarities. The film (12) is extruded hot, as a layer between first and second substrates (1, 2). This assembly is calendered, bonding the layers. The bond between first substrate and polymer film is chemical. Following cooling, that between second substrate and film is weak. It is of an electrical, mechanical and chemical nature. Preferred features: prior to laminar extrusion, the internal face (11) of the first substrate (1) is treated by a corona discharge carried out at 1000-2000 Dyn (sic). Laminar extrusion of the polymer film is carried out at 230-350 degrees C. Substrates are made with coverings on at least those surfaces facing the polymer film.

Abstract (fr)  
L'invention concerne un procédé d'assemblage temporaire d'un premier substrat (1) avec un second substrat (2), caractérisé en ce qu'on charge électrostatiquement un film polymère (12) et/ou le second substrat (2) avec des polarités opposées, on effectue l'extrusion couchage à chaud du film polymère chargé (12), de façon intercalaire entre le premier substrat (1) et le second substrat (2) et on effectue le calandrage de l'ensemble de façon à créer, d'une part, une liaison forte de nature essentiellement chimique entre le premier substrat et le film polymère et, d'autre part, après refroidissement, des liaisons faibles de natures, électrique et mécanique entre le second substrat (2) et le film polymère (12). <IMAGE>

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Citation (search report)

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